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Application ID: 10665651 *10665651*
Title of Invention: THIN AND HEAT RADIANT
SEMICONDUCTOR PACKAGE AND
METHOD FOR MANUFACTURING
First Named Inventor: Jae Ku
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TRANSMITTAL

Electronic Version v1.1

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Title of Invention	THIN AND HEAT RADIANT SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING	
<p>Application Number: 10/665651 *10/665651*</p> <p>Date: 2003-09-19</p> <p>First Named Applicant: Jae Hun Ku</p> <p>Confirmation Number: 6079</p> <p>Attorney Docket Number: AMKOR041G</p>		
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Submitted by:	Elec. Sign.	Sign. Capacity
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney

Documents being submitted us-ids	Files ids4-usidst.xml us-ids.dtd us-ids.xsl
Comments	

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	THIN AND HEAT RADIANT SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING									
Application Number:	10/665651				*10/665651*					
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First Named Applicant:	Jae Ku									
Attorney Docket Number:	AMKOR041G									
Art Unit:	2811									
Search string:	(5909053 or 5915998 or 5917242 or 5939779 or 5942794 or 5951305 or 5959356 or 5969426 or 5973388 or 5976912 or 5977613 or 5977615 or 5977630 or 5981314 or 5986333 or 5986885 or 6001671 or 6013947 or 6018189 or 6020625 or 6025640 or 6031279 or RE36613 or 6034423 or 6040626 or 6043430 or 6060768 or 6060769 or 6072228 or 6075284 or 6081029 or 6084310 or 6087715 or 6087722 or 6100594 or 6113474 or 6118174 or 6118184 or 6130115 or 6130473 or RE36907 or 6133623 or 6140154 or 6143981 or 6169329 or 6177718 or 6181002 or 6184465 or 6184573 or 6194777).pn.									
US Patent Documents										
Note: Applicant is not required to submit a paper copy of cited US Patent Documents										
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass			
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Signature

Examiner Name	Date